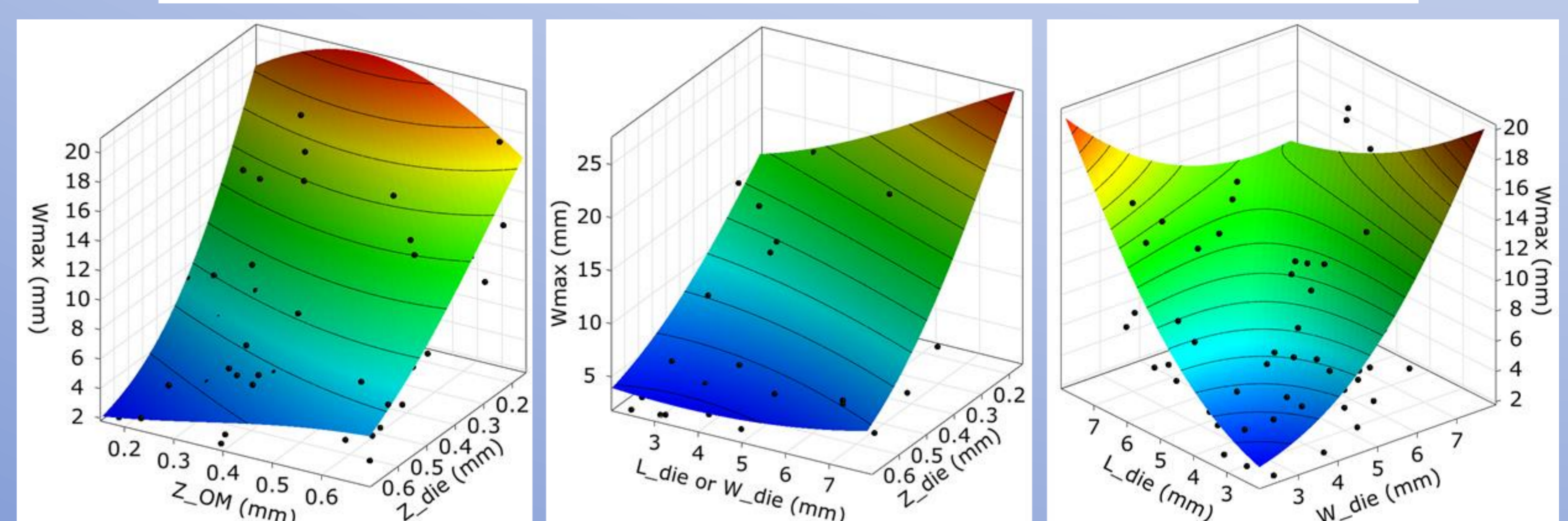
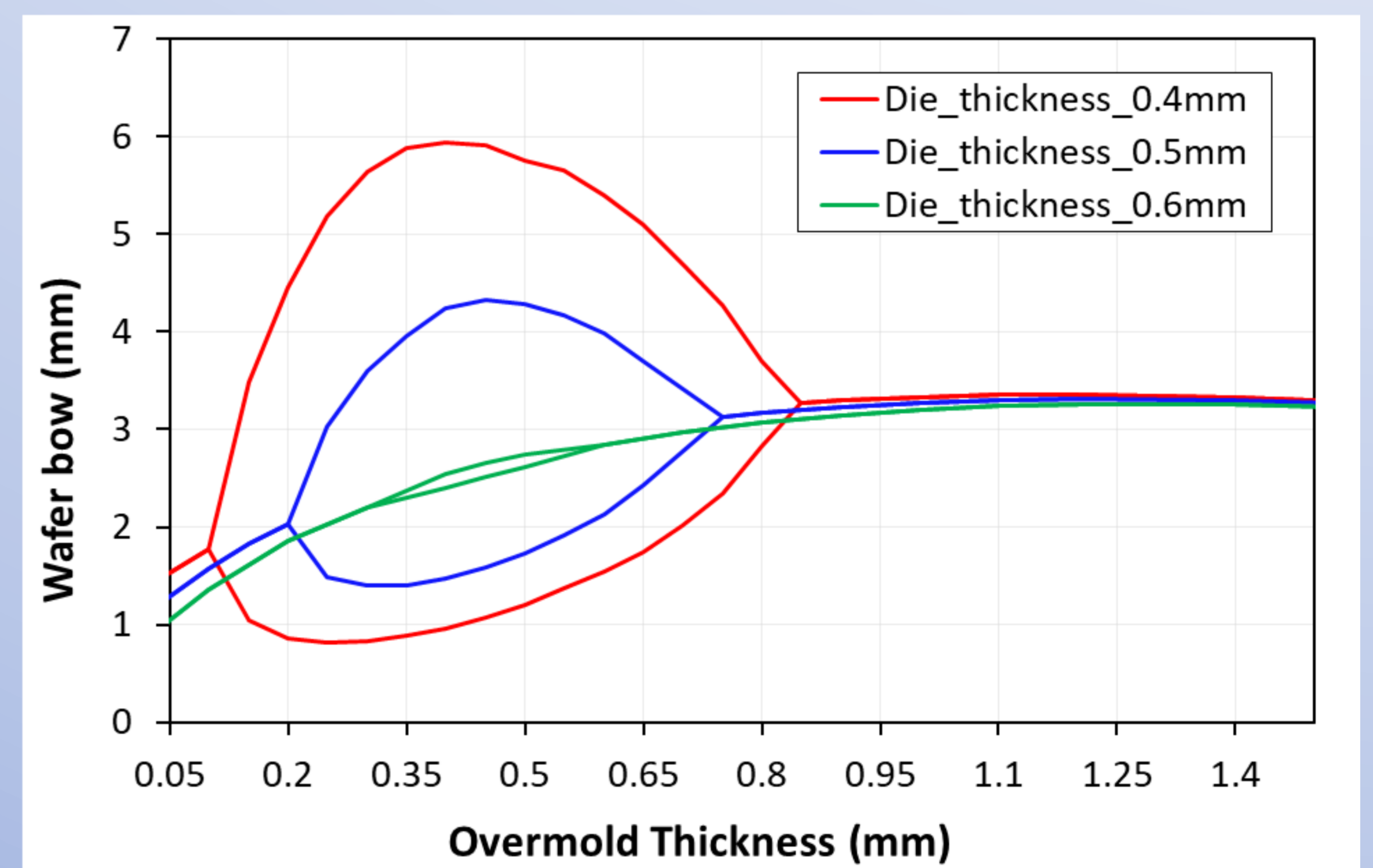
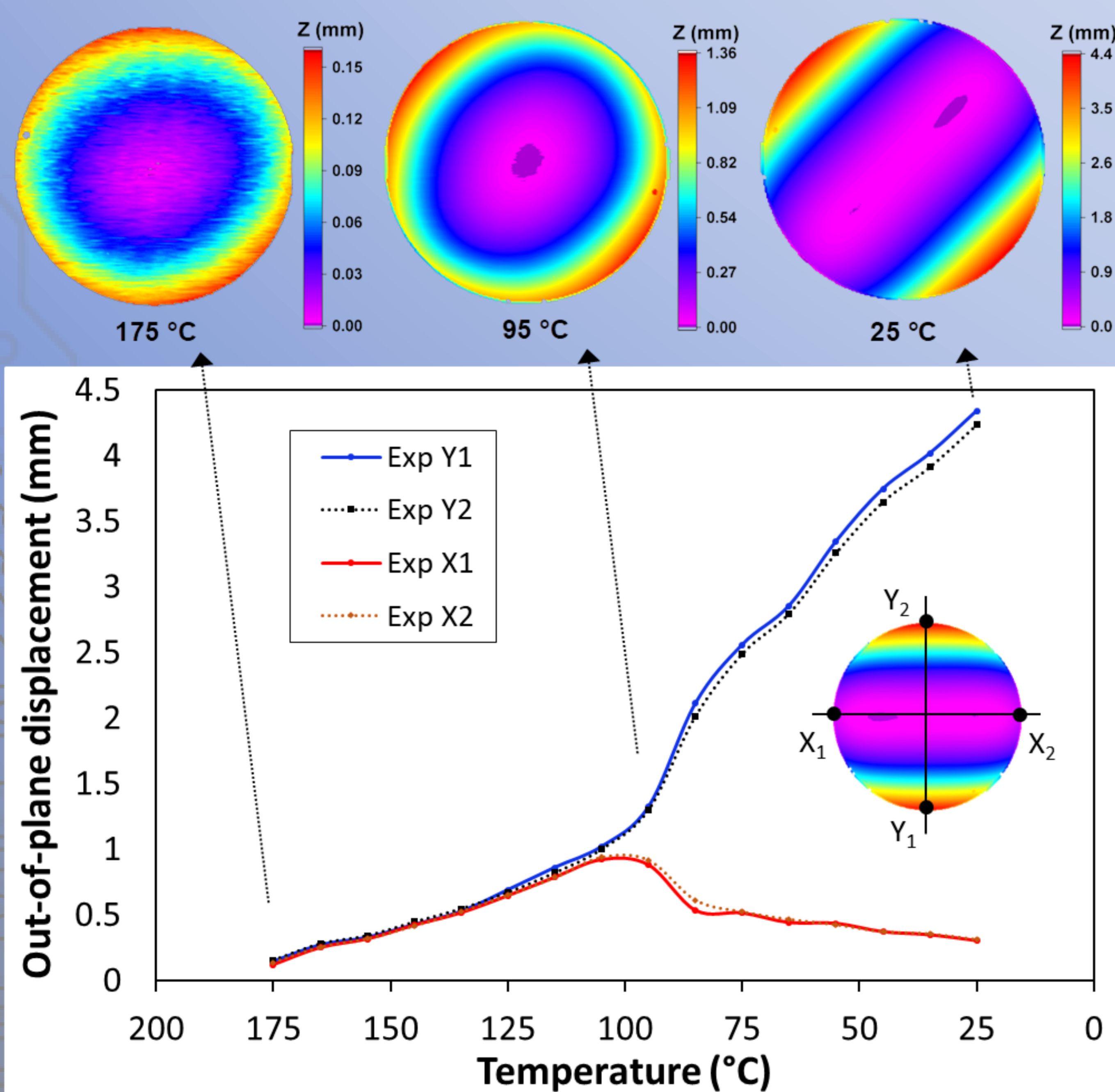


EuroPAT MASiP

EuroPAT-MASiP team from Fraunhofer ENAS, Besi NL and Amkor has been rewarded with the **Outstanding Paper Award** at [ASME 2020 InterPACK Conference](#) for their paper “*The Systematic study of Fan-Out Wafer Warpage Using Analytical, Numerical and Experimental Methods*” .

The paper focuses on characterizing the physics of wafer warpage, which is a challenge for many process steps in fan-out wafer-level packaging (FoWLP) technologies used for heterogeneous system integration. The new study provides recommendations and good practical guidance for improving the design and optimizing the process flow of FoWLP solutions with increased product yield and reliability.



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